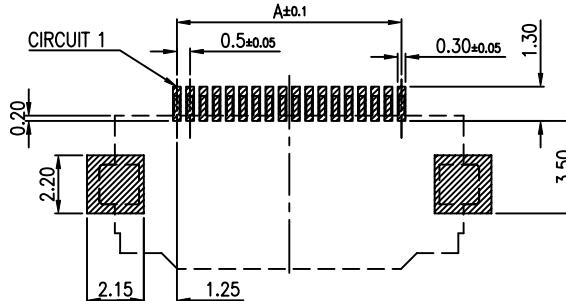
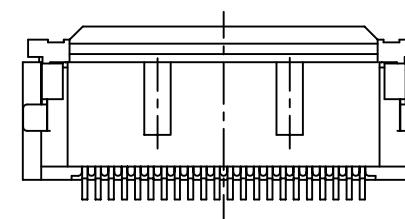
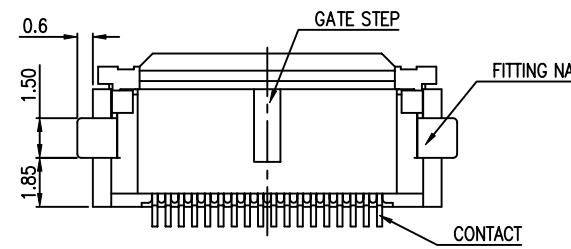


COVER OPEN STATE



RECOMMENDED PC BOARD PATTERN DIM.(REF.)

NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL 94V-0
- 1.2 ACTUATOR: THERMOPLASTIC, HIGH TEMP., UL 94V-0
- 1.3 CONTACT: COPPER ALLOY
- 1.4 FITTING NAIL: COPPER ALLOY

2. FINISH:

UNDER PLATING: 50 μ MIN. NICKEL OVERALL
CONTACT AREA AND SOLDER TAIL: GOLD FLASH OVERALL
FITTING NAIL:
UNDER PLATING: 50 μ MIN. NICKEL OVERALL
MATTE TIN PLATING 100 μ MIN. OVERALL

3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP.
FOR 10 SECONDS MAX.
4. SPEC. PLS. REFER TO GS-12-578.
5. PACKAGE PLS. REFER TO GS-14-1330.

6. PART NUMBER DESCRIPTION

10089708-XXX	0	1	X	LF
NO. OF CONTACTS(CKT)				LEAD FREE
PACKING:	X: HOUSING ACTUATOR	C: NATURAL BLACK		COLOR
	0: TAPE & REEL			PLATING 1: GOLD FLASH OVERALL

CKT	DIM. A	DIM. B	DIM. C
004	1.50	2.56	6.2
006	2.50	3.56	7.2
008	3.50	4.56	8.2
010	4.50	5.56	9.2
012	5.50	6.56	10.2
014	6.50	7.56	11.2
016	7.50	8.56	12.2
026	12.50	13.56	17.2
030	14.50	15.56	19.2

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	angles		
A	T08-1182	WL	11/06/08	.X ± 0.25	.XX ± 0.15	projection	title 0.5mm FPC CONN. SMT R/A B/C TYPE
B	T08-1196	WL	12/10/08	.XXX ± 0.10	0° ± 2°		
C	T09-1005	WL	01/20/09			MM	product family FPC
D	T09-1132	WL	10/15/09	dr LEIF SHEN	08-06-18		code SNG
E	T10-0046	WL	04/15/10	engr DENNIS GOH	08-08-08	size dwg no	
F	T10-0108	WL	07/02/10	chr DENNIS GOH	08-08-08	scale	
				appd JOEY NG	08-08-08	sheet A4	10089708
sheet index	revision sheet	F	1			sheet 1	1 of 1